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Benjamin N. ELDRIDGE *et al.*
Appl. No. 09/364,788*Amendments to the Claims*

Please cancel claims 76-79 without prejudice or disclaimer.

Please amend claims 58 and 67 as follows:

58. (Twice Amended) An electronic component comprising:

a substrate including a conductive area;

a connecting layer coupling the conductive area to internal circuitry within the electronic component;

a passivation layer disposed on a surface of said substrate, said passivation layer having an opening at said conductive area of said substrate;

at least one electrically conductive layer disposed on said passivation layer and on said conductive area of said substrate; and

a resilient, conductive contact [contract] structure comprising (i) a base portion electrically coupled through said at least one at least one electrically conductive layer to said conductive area of said substrate, (ii) a tip portion displaced away from said substrate and said conductive area, and (iii) a beam portion between said base portion and said tip portion, wherein:

a length of said beam portion extends from said base portion to said tip portion, and

a width of said beam portion decreases along said length from said base portion to said tip portion.

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59. (Previously Added) The electronic component of claim 58, wherein said conductive area comprises a terminal.

60. (Previously Added) The electronic component of claim 58 further comprising a terminal on said substrate, said terminal being electrically connected to said conductive area.

61. (Previously Added) The electronic component of claim 58, wherein said tip portion includes a pointed end.

62. (Amended) The electronic component of claim 58, wherein said substrate comprises a semiconductor device.

63. (Previously Added) The electronic component of claim 58, wherein said contact structure comprises a metal layer.

64. (Previously Added) The electronic component of claim 63, wherein said contact structure comprises a plurality of metal layers.

65. (Previously Added) The electronic component of claim 58 further comprising a plurality of said contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

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66. (Previously Added) The electronic component of claim 58, wherein said tip portion comprises a beveled peripheral edge.

67. (Twice Amended) An electronics system comprising:

a first substrate including a conductive area;

a connecting layer coupling the conductive area to internal circuitry within the electronics system;

a passivation layer disposed on a surface of said first substrate, said passivation layer having an opening at said conductive area of said first substrate;

at least one electrically conductive layer disposed on said passivation layer and on said conductive area of said first substrate; [and]

a resilient conductive contact structure comprising (i) a base portion electrically coupled through said at least one at least one electrically conductive layer to said conductive area of said first substrate, (ii) a tip portion displaced away from said first substrate, and (iii) a beam portion between said base portion and said tip portion, wherein a length of said beam portion extends from said base portion to said tip portion, and a width of said beam portion decreases along said length from said base portion to said tip portion; and

a second substrate including a conductive contact element in physical contact with said contact structure and deflecting said contact structure, said contact structure exerting a force against said contact element due to said resiliency of said contact structure.

68. (Previously Added) The electronics system of claim 67, wherein said conductive area comprises a terminal.

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69. (Previously Added) The electronics system of claim 67 further comprising a terminal on said first substrate, said terminal being electrically connected to said conductive area.

70. (Previously Added) The electronics system of claim 67, wherein said tip portion includes a pointed end.

71. (Amended) The electronics system of claim 67, wherein said first substrate comprises a semiconductive device.

72. (Previously Added) The electronics system of claim 67, wherein said contact structure comprises a metal layer.

73. (Previously Added) The electronics system of claim 67, wherein said contact structure comprises a plurality of metal layers.

74. (Previously Added) The electronics system of claim 67 further comprising a plurality of said contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

75. (Previously Added) The electronics system of claim 67, wherein said tip portion comprises a beveled peripheral edge.

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76. (Cancelled) The electronic component of claim 58, wherein said at least one electrically conductive layer includes:

a shorting layer; and

a conductive layer; said shorting layer being provided between said conductive layer and said surface of said substrate.

77. (Cancelled) The electronic component of claim 76, wherein said at least one electrically conductive layer further includes a seed layer provided between said conductive layer and said base portion of said resilient conductive contact structure.

78. (Cancelled) The electronics system of claim 67, wherein said at least one electrically conductive layer includes:

a shorting layer; and

a conductive layer; said shorting layer being provided between said conductive layer and said surface of said substrate.

79. (Cancelled) The electronics system of claim 78, wherein said at least one electrically conductive layer further includes a seed layer provided between said conductive layer and said base portion of said resilient conductive contact structure.